AMENDMENTS TO THE CLAIMS

- 1. (Currently Amended) A compound for producing a heat-ray cutoff film, which-comprisinges a dispersion sol including conductive nanoparticles uniformly dispersed in an amphoteric-amphiphilic solvent.
- 2. (Currently Amended) The compound according to claim 1, wherein the conductive nanoparticles include at least one of ATO, ITO, and AZO.
- 3. (Currently Amended) The compound according to claim 1, wherein the conductive nanoparticles have is sized in diameters under 200 nm-and in the range of 1-80 wt%, while, and the amphoteric amphiphilic solvent has is present in a range of 20 ~ 99 wt % relative to the dispersion sol.
- 4. (Currently Amended) The compound according to claim 3, wherein the amphoteric amphiphilic solvent includes ethylene glycol monomethyl ether, ethylene glycol monoethyl ether, ethylene glycol monopropyl ether, or ethylene glycol monobutyl ether.
- 5. (Original) The compound according to claim 1, which further comprises an acid for adjusting surface charges of the conductive nanoparticles, the acid including an organic acid, an inorganic acid, or polymeric acid.
- 6. (Currently Amended) The compound according to claim 5, wherein the conductive nanoparticles are is an ATO nanoparticles containing Sb with 5 ~ 20 wt %

 Sb, and the acid is present in a included with the range of 5x10⁻⁴ ~ 3.5x10⁻³ g to the

conductive nanoparticle.

- 7. (Previously Presented) The compound according to claim 1, which further comprises a dispersing agent for stabilizing the conductive nanoparticles.
- 8. (Currently Amended) The compound according to claim 7, wherein the dispersing agent is present in a range of included with 1 ~ 30 wt % relative to the dispersion sol-conductive nanoparticle, while the dispersing agent includinges a dispersing agent containing an amine radical, a dispersing agent containing an acid radical, or a neutral dispersing agent.
- 9. (Currently Amended) The compound according to claim 7, which further comprises <u>a more one</u> resin binder <u>selected from among</u> an anti-hydrolic resin binder. and a hydrolic <u>resin binder</u>, or <u>an alcoholic resin binder</u>.
- 10. (Currently Amended) The compound according to claim 9, wherein the resin binder is <u>present</u> in <u>a the-range</u> of 1 ~ 95 wt_% <u>relative to the compound</u>.
- the hydrolic resin binder <u>is selected from includes</u>—a water-soluble alkyd, a polyvinylalcohol, a polybutylalcohol, an acrylic, an acrylylstylene, or a super-acid vinyl;

 the alcoholic resin binder <u>is selected from includes</u>—a polyvinylbutyral or a polyvinylacetal;

 the anti-hydrolic resin binder <u>is includes</u>—a heat-hardening resin binder <u>or an</u>

ultraviolet-hardening resin binder, the heat-hardening resin binder selected from including an acrylic, a polycarbonate, a polychloride vinyl, an urethane, a melamine, an alkyd, a polyesther, or an epoxy, and the or an ultraviolet-hardening resin binder selected from including an epoxy acrylylate, a polyether acrylyate, a polyesther acrylylate, or an urethane-metamorphosed acrylylate.

- 12. (Currently Amended) The compound according to claim 9, wherein the conductive nanoparticles have is sized in diameters under 200 nm and in the range of 1 ~ 80 wt%, while, and the amphoteric amphiphilic solvent has is present in a range of 20 ~ 99 wt % relative to the dispersion sol.
- 13. (Currently Amended) The compound according to claim 12, wherein the amphoteric amphiphilic solvent includes ethylene glycol monomethyl ether, ethylene glycol monoethyl ether, ethylene glycol monopropyl ether, or ethylene glycol monobutyl ether.
- 14. (Currently Amended) The compound according to claim 12, wherein the conductive nanoparticles are is an ATO nanoparticles containing Sb with 5 ~ 20 wt_% Sb, and the acid is present in a included with the range of 5x10-4 ~ 3.5x10-3 g to the conductive nanoparticle.
- 15. (Currently Amended) The compound according to claim 12, wherein the dispersing agent is present in a range of included with $1 \sim 30$ wt % relative to the dispersion sol conductive nanoparticle, while the dispersing agent includinges a dispersing agent containing an amine radical, a dispersing agent containing an acid

radical, or a neutral dispersing agent.

- 16. (Currently Amended) A method of forming a compound for producing a heat-ray cutoff film, which-comprisinges uniformly dispersing conductive nanoparticles uniformly in an amphoteric amphibilic solvent.
- 17. (Currently Amended) The method according to claim 16, wherein the conductive nanoparticles have is sized in-diameters under 200 nm and in the range of 1 ~ 80 wt%, while, and the amphoteric amphiphilic solvent has is present in a range of 20 ~ 99 wt % relative to the dispersion sol.
- 18. (Currently Amended) The method according to claim 16, wherein the conductive nanoparticles are dispersed in the amphoteric amphiphilic solvent by means of a dispersing agent and at least more one among acids to adjust surface charges of the conductive nanoparticles are adjusted with an acid.

20. (Currently Amended) A method of forming a heat-ray cutoff film, comprising the steps of:

mixing the compound <u>formed by the method of defined in-claim 19</u> with <u>a one</u> more resin binders among <u>selected from an</u> anti-hydrolic resin binder, and a hydrolic resin binder, or an alcoholic resin binder to obtain a mixed composite; and

depositing the mixed composite on a substrate and hardening the deposited composite with by a chemical ray using an-ultraviolet radiation, or an electronic ray, or by heat.

- 21. (Currently Amended) The method according to claim 20, wherein the resin binder-has is present in a range of 1 ~ 95 wt_% relative to the compound.
- 23. (Currently Amended) The method according to claim 20, wherein the substrate is a polycarbonate-series resin, a poly (metha) acrylylest[[h]]er-series resin, a saturated fatty acid, or a cyclo-olefin resin,-and the substrate hardened by an ultraviolet radiation.
 - 24. (Currently Amended) The method according to claim 23, wherein the

<u>substrate</u> is exposed to ultraviolet <u>radiation</u> is irradiated in the range of 500 ~ 1500 mJ/cm, while the <u>substrate</u> is conveyed at a and the hardening proceeds in the velocity of 15 ~ 50 m/min.

- 25. (Original) A heat-ray cutoff film manufactured by the method as defined in claim 18.
- 26. (Currently Amended) A heat-ray cutoff film manufactured by the method[[s]] as defined claim 19.
- 27. (Currently Amended) The heat-ray cutoff film according to claim 26, wherein the film has a surface resistance of $106 \Omega/\Box 1 \times 10^6 \Omega \cdot cm$.
- 28. (Currently Amended) The heat-ray cutoff film according to claim 26, wherein the film has <u>a</u> thickness <u>of less than under-5 μm</u>, <u>a</u> pencil intensity above 1H, a visible light transmittance above 50%, and <u>a</u> heat-ray cutoff rate of 50%.
- 29. (Currently Amended) A method of screening heat rays, comprising:

 by-attaching a the-heat-ray cutoff film on a vessel-containing drinking water,

 the heat-ray cutoff film formed from a dispersion sol including an amphiphilic solvent

 preventing the heat rays from going in and out of the vessel to retain temperature of
 the drinking water.
- 30. (Currently Amended) A method of screening heat rays with a heat-ray cutoff film, comprising the steps of:

forming a compound <u>including a dispersion sol with</u>by <u>uniformly dispersing</u>
conductive nanoparticles <u>uniformly dispersed</u> in an <u>amphoteric amphiphilic</u> solvent;

mixing the compound with <u>a one-more-resin</u> binder[[s]] <u>selected from among an</u> anti-hydrolic resin binder, and a hydrolic <u>resin binder</u>, or <u>an alcoholic resin binder to obtain a mixed composite</u>;

depositing the mixed composite of the compound and resin binder on a substrate and then forming the heat-ray cutoff film by hardening the deposited composite with by a chemical ray using an ultraviolet radiation, or an electronic ray, or by heat to form the heat-ray cutoff film; and

coating the heat[[r]]-ray cutoff film on a surface of a vessel-containing a content.

- 31. (Currently Amended) The method according to claim 30, wherein the conductive nanoparticles have is sized in-diameters under 200 nm and in the range of 1 ~80 wt%, while, and the amphoteric amphiphilic solvent has is present in a range of 20 ~ 99 wt % relative to the dispersion sol.
- 32. (Currently Amended) The method according to claim 30, wherein the conductive nanoparticles are dispersed in the amphoteric amphiphilic solvent by means of a dispersing agent and at least more one among acids to adjust surface charges of the conductive nanoparticles are adjusted with an acid.
- 33. (Currently Amended) The method according to claim 32, wherein:

 the conductive nanoparticles are is an ATO nanoparticles containing Sb with 5

 20 wt_%_Sb;

 the acid is present in a included with the range of 5x10-4 ~ 3.5x10-3 g-to-the

conductive nanoparticle,; and

_____the dispersing agent is <u>present in a range of included with-1 ~ 30 wt_% relative</u> to the <u>dispersion sol-conductive nanoparticle</u>, <u>and-the dispersing agent includinges a</u> dispersing agent containing an amine radical, a dispersing agent containing an acid radical, or a neutral dispersing agent.

- 34. (Currently Amended) The method according to claim 30, wherein the resin binder is present in a range of has-1 ~ 95 wt % relative to the compound.
- 35. (Currently Amended) The method according to claim 30, wherein the substrate is a polycarbonate-series resin, a poly (metha) acrylylest[[h]]er-series resin, a saturated fatty acid, or a cyclo-olefin resin,—and_the substrate hardened by an ultraviolet radiation.
- 36. (Original) The method according to claim 30, wherein the vessel is made of a metal, a ceramic, or a plastic, containing drinking waters or foods.